IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier Inforr	nation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-19				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Request	Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	Version	N	Manufacturing Site		ght*	UOM	Unit Type
		NRVUS220VT3G- GA01 REC SMB SPEC		REC SMB SPECIA	AL ULTFST		2024-05-19 CNP		NP	103.	1939	mg	Each	
<b>Ianufacturing</b>	<b>Process Informat</b>	ion												
Terminal Plating / Grid Array Material Te			Perminal Base Alloy J-STD-020 MSL		L Rating	Peak Process Body Temperature Max Time at		e Max Time at Peak	Temperature	Numbe	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		C	CU Alloy 1				260		C	30	seconds	3		
omments														
vel 1 - maximum	time at peak temperatui	re during sol	dering is 10-3	30 seconds										
or more informat	ion regarding material o	composition 1	olease refer t	o page 3	•	•		•		_		•		_

<b>RoHS Material Composition Declaration</b>			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cornel to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Sta											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).  Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	8.2	mg	Supplier	Iron (Fe)	7439-89-6		0.0082	mg
			Supplier	Copper (Cu)	7440-50-8		8.1893	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0025	mg
Die	0.8039	mg	Supplier	Silicon (Si)	7440-21-3		0.7959	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.008	mg
Die Attach Solder	1.62	mg	Supplier	Silver (Ag)	7440-22-4		0.0405	mg
			A	Lead (Pb)	7439-92-1	7a	1.4985	mg
			Supplier	Tin (Sn)	7440-31-5		0.081	mg
Lead Frame	33.6	mg	Supplier	Iron (Fe)	7439-89-6		0.0336	mg
			Supplier	Copper (Cu)	7440-50-8		33.5563	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0101	mg
Mold Compound-Black	55.19	mg	Supplier	Polycondensate of 4,4'-bis(methoxymethyl)biphenyl and phenol	205830-20-2		1.3798	mg
			Supplier	Triphenylphosphine	603-35-0		0.2759	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.2759	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.2759	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5519	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.671	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.7595	mg
Plating	3.78	mg	Supplier	Tin (Sn)	7440-31-5		3.78	mg